

## **IN THE CLAIMS**

Please amend the claims in accordance with the following rewritten claims in clean form. Applicant includes herewith an Attachment for Claim Amendments showing a marked up version of each amended claim.

1. (Twice Amended) A manufacturing method for manufacturing an electro-optical device having an electro-optical panel with a substrate holding an electro-optical material and a mount base member bonded to the substrate, the manufacturing method comprising:

a step of connecting a first terminal bank, formed on the surface of the substrate, to a second terminal bank formed on the surface of the mount base member, the second terminal bank being at a pitch which is smaller than a pitch of the first terminal bank when the substrate is thermal compression bonded to the mount base member, the mount base member having a linear thermal expansion coefficient that is larger than a linear thermal expansion coefficient of the substrate,

wherein the connection step directly connects the first terminal bank to the second terminal bank such that the pitch of the first terminal bank and the pitch of the second terminal bank become substantially equal to each other when the substrate and the mount base member are deformed during the thermal compression bonding of the substrate and the mount base member.

9. (Twice Amended) A terminal connection method for connecting a first terminal bank formed on the surface of a first base member to a second terminal bank formed on the surface of a second base member, the connection method comprising the steps of:

fabricating the second terminal bank at a pitch that is smaller than a pitch of the first terminal bank, the second base member having a linear thermal expansion coefficient that is larger than a linear thermal expansion coefficient of the first base member; and

directly connecting the first terminal bank to the second terminal bank;

thermal compression bonding the first base member to the second base member; and

during the thermal compression bonding step, deforming the first base member and the second base member such that the pitch of the first terminal bank and the pitch of the second terminal bank become substantially equal.

14. (Amended) An electro-optical device comprising:

an electro-optical panel including a substrate holding an electro-optical material;

a mount base member thermal-bonded to the substrate, said mount base member having a linear thermal expansion coefficient that is larger than a linear thermal expansion coefficient of the substrate;

a first terminal bank formed on the surface of the substrate;

a plurality of first alignment marks formed and mutually spaced apart on the surface of the substrate;

a second terminal bank formed and mutually spaced apart on the mount base member, wherein the second terminal bank is directly connected to the first terminal bank at a pitch thereof substantially equal to the pitch of the first terminal bank; and

a plurality of second alignment marks formed on the surface of the mount base member, and spaced mutually more apart than the spacing of the first alignment marks.

23. (Amended) A mount base member to be bonded to a substrate of an electro-optical panel, comprising:

a second terminal bank formed at a pitch that is smaller than a pitch of a first terminal bank formed on the substrate, the second terminal bank directly connected to the first terminal bank; and

a linear thermal expansion coefficient that is larger than a thermal expansion coefficient of the substrate.